



503.39864X00 / P5829/AM

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Toshiya SATOH et al.  
Serial No.: 09/809,181  
Filed: 16 March 2001  
For: SEMICONDUCTOR DEVICE AND MANUFACTURING  
METHOD FOR HIGH RELIABILITY AND PRODUCTION YIELD  
RATE WITH MINIMAL DAMAGE DUE TO APPLICATION OF  
MECHANICAL STRESS AND THERMAL STRESS  
Group: 2815  
Examiner: Jose R. Diaz  
Conf. No.: 5733

**AMENDMENT**

**Mail Stop Amendment**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

16 March 2005

Sir:

In response to the Office Action mailed 16 November 2004 in connection with the above-identified application, the following amendments and remarks are respectfully submitted.

In accordance with 37 CFR §1.121 in the Final Rule effective 30 July 2003, and as revised in the Final Rule effective 21 October 2004, each section of amendment begins on a new page, and changes are shown by strike-through (or double brackets where appropriate) and underlining to indicate deletions and additions, respectively. A complete listing of all claims ever presented in the application is given with the current status of each claim, and only the text of all pending and withdrawn claims is presented in full, with those pending/withdrawn claims not being amended herein being presented in clean version.